

Ajit V. Sathe et al.

SOLDERLESS ELECTRONICS PACKAGING AND METHODS OF MANUFACTURE

Docket No.:

884.341US1

Filed:

November 30, 2000

Examiner:

Xuan Thai

Customer No.: 21186

Serial No.: 09/726629

Due Date: N/A

Group Art Unit: 2181 Confirmation No.: 2086

RECEIVED

OCT 0 8 2003

Technology Center 2100

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

• We are transmitting herewith the following attached items (as indicated with an "X"):

A return postcard.

Formal Drawings (13 pgs.).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

Atty: Ann M. McCrackin

Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this **30** day of September, 2003.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

(GENERAL)